Patronage Sponsorship Program

March 29-31, 2015, Austin, Texas USA



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IEEE International Symposium on Power Line Communications and its Applications





The 2015 IEEE International Symposium on Power Line Communications and its Applications (ISPLC) will be held March 29 -31, 2015, in the Blanton Art Museum Complex on The University of Texas at Austin campus. Austin has a population of 1M people and is the Capitol of the State of Texas (Capitol Building pictured above on right). Downtown Austin (pictured above on left) has a dynamic live music scene, hike & bike trails, museums, and the UT Austin campus.

Austin is a high-tech hub. Dell, Freescale Semiconductor, National Instruments and Silicon Labs are based here. Austin has major design centers for AMD, Apple, ARM, AT&T, Broadcom, Cirrus Logic, IBM, Intel, and Qualcomm, among others.

ISPLC 2015 will bring together academic and industry professionals to present and discuss state of the art solutions and research results on existing and future power line communication (PLC) systems, PLC applications, and PLC standardization activities. The contributions presented at ISPLC will span all aspects of communications over power lines, including access, home networking, in-vehicle applications, utility applications, smart grids, green communications and more. Topics from related fields such as wireless that highlight analogies or differences with PLC and stimulate cross-fertilization will be discussed.

ISPLC has been a successful conference for 19 years, and it is recognized as the major international conference in the PLC field. ISPLC 2015 will have the participation of utilities (telecom, electric, water, and gas), regulatory agencies (energy and telecom), governmental institutions, R&D institutes, universities, manufacturers, and technology/solution providers/integrators.

Each year, ISPLC seeks companies to participate in its Patron Sponsor Program. Being a patron provides an opportunity for companies to advertise and increase their visibility within the IEEE community and other public and private organizations. It gives an opportunity to highlight and showcase products, services and expertise, and to create brand awareness and preference, generate consumer loyalty and enhance the corporate image. Contacts with researchers, network operators, power utilities, and others will be available at the symposium.

Several flexible options are given below. Full conference registration includes all technical sessions, panel discussion, tutorial, keynote talks, and banquet. Contact Information: Prof. Brian L. Evans, General Chair, bevans@ece.utexas.edu.

	Cost	Logo on everything	Exhibit Space	Full Conf. Registration	Advertisement in program	Pitch at banquet	Technical program
Gold	\$10k	Yes	2 tables	4 people	1 page	120 s	give keynote
Silver	\$ 5k	Yes	1 table	2 people	½ page	60 s	60s intro
Bronze	\$ 2k	Yes	1 table	1 person	1/4 page	30 s	30s intro